

| L Number | Hits    | Search Text   | DB  | Time stamp       |
|----------|---------|---|---|------------------|
| -        | 114427  | electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:03 |
| -        | 251638  | seed\$4   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:05 |
| -        | 1837550 | fill\$4 or refill\$4  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 10:12 |
| -        | 1159899 | copper or cu  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 09:02 |
| -        | 697397  | photoresist or resist or photosensitive or photo adj2 sensitive   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 12:58 |
| -        | 1173993 | wiring or interconnect\$4 or inter adj2 connect\$4  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 09:04 |
| -        | 392748  | harden\$4   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 09:42 |
| -        | 5058080 | groove or trench or hole or aperture or opening   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:04 |
| -        | 7713    | (copper or cu) with (fill\$4 or refill\$4) with (groove or trench or hole or aperture or opening)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 10:14 |
| -        | 13795   | seed\$4 with (groove or trench or hole or aperture or opening)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 10:14 |
| -        | 597     | ((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same ((copper or cu) with (fill\$4 or refill\$4) with (groove or trench or hole or aperture or opening)) same (seed\$4 with (groove or trench or hole or aperture or opening))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 10:17 |
| -        | 276     | ((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same ((copper or cu) with (fill\$4 or refill\$4) with (groove or trench or hole or aperture or opening)) same (seed\$4 with (groove or trench or hole or aperture or opening))) and (photoresist or resist or photosensitive or photo adj2 sensitive) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 14:28 |

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|---|---------|---|---|------------------|
| - | 114427  | electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 12:58 |
| - | 995720  | photoresist or resist or photosensitive or photo adj2 sensitive or polymeric  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 12:59 |
| - | 2422381 | (photoresist or resist or photosensitive or photo adj2 sensitive or polymeric ) or polymer or polyimide   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:00 |
| - | 1175302 | hard or hardern\$4 or cure\$1 or curing   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:02 |
| - | 107409  | ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric ) or polymer or polyimide) with (hard or hardern\$4 or cure\$1 or curing)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:03 |
| - | 114427  | electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:04 |
| - | 5058080 | groove or trench or hole or aperture or opening   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:04 |
| - | 251638  | seed\$4   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:05 |
| - | 2413    | (electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4 ) same (groove or trench or hole or aperture or opening ) same seed\$4  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:07 |
| - | 12579   | (metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (remov\$3) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric ) or polymer or polyimide)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 14:12 |
| - | 164     | ((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4 ) same (groove or trench or hole or aperture or opening ) same seed\$4 ) and ((metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (remov\$3) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric ) or polymer or polyimide)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:13 |

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|---|------|--|---|------------------|
| - | 82   | ((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4 ) same (groove or trench or hole or aperture or opening ) same seed\$4 ) and ((metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (remov\$3) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric ) or polymer or polyimide))) and (hard or hardern\$4 or cure\$1 or curing) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:40 |
| - | 4707 | 438/618.ccls. or 438/622.ccls. or 438/623.ccls. or 438/637.ccls.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:40 |
| - | 453  | (438/618.ccls. or 438/622.ccls. or 438/623.ccls. or 438/637.ccls.) and (electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4 ) and seed\$4   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 13:40 |
| - | 1492 | (metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (liftoff or lift\$3 adj2 off) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric ) or polymer or polyimide)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 14:13 |
| - | 10   | ((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4 ) same (groove or trench or hole or aperture or opening ) same seed\$4 ) and ((metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (liftoff or lift\$3 adj2 off) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric ) or polymer or polyimide))                             | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/01 14:14 |